

Dual N-channel MOSFET

KFCAB21830L Datasheet

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1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET for lithium-ion secondary battery protection circuits.

2. FEATURES

- Source-source On-state Resistance: $R_{SS(on)}$ typ = 2.5 m Ω (V_{GS} = 3.8 V)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

3. MARKING SYMBOL: W6

4. PACKAGING

Embossed type (Thermo-compression sealing): 10,000 pcs / reel (standard)

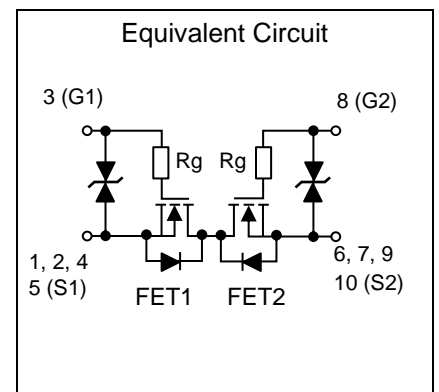
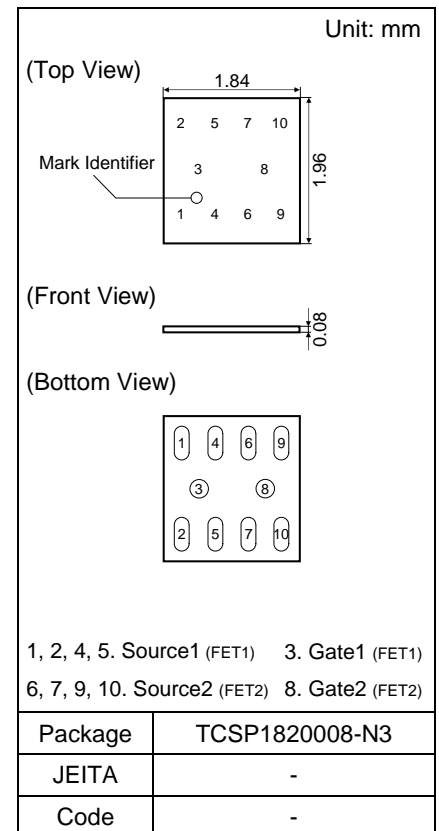
5. ABSOLUTE MAXIMUM RATINGS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	12	V
Gate-source Voltage	VGS	± 8	V
Source Current	DC ^{*1}	IS1	A
	DC ^{*2}	IS2	
	DC ^{*3}	IS3	
	Pulsed ^{*4}	ISp	
Total Power Dissipation	DC ^{*1}	PD1	W
	DC ^{*2}	PD2	
	DC ^{*3}	PD3	
Operating Junction and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150	$^\circ\text{C}$

6. THERMAL CHARACTERISTICS $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	R_{th1} ^{*1}	245	$^\circ\text{C} / \text{W}$
	R_{th2} ^{*2}	74	
	R_{th3} ^{*3}	39	

- Note
- *1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board partially covered with copper pad (22 mm² area, 36 μm thickness).
 - *2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board fully covered with copper pad (604 mm² area, 36 μm thickness).
 - *3 Mounted on ceramic board (70 mm x 70 mm x t1.0 mm).
 - *4 $t = 10 \mu\text{s}$, Duty Cycle $\leq 1\%$.



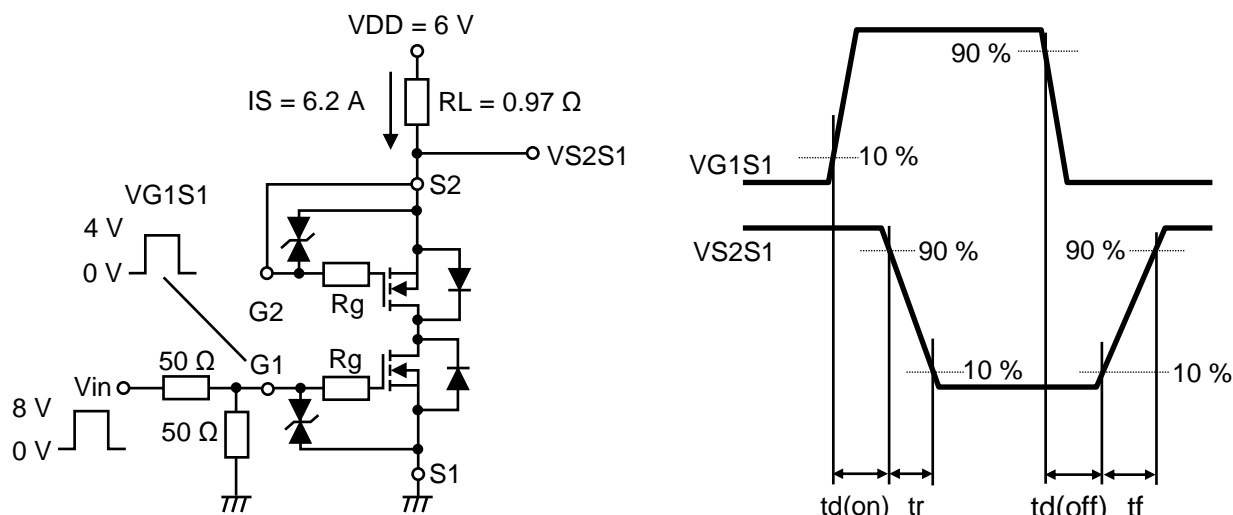
7. ELECTRICAL CHARACTERISTICS $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	12			V
Zero Gate Voltage Source Current	ISSS	VSS = 12 V, VGS = 0 V			1	μA
Gate-source Leakage Current	IGSS1	VGS = ± 8 V, VSS = 0 V			± 10	μA
	IGSS2	VGS = ± 5 V, VSS = 0 V			± 1	
Gate-source Threshold Voltage	Vth	IS = 0.56 mA, VSS = 6 V	0.35	0.90	1.40	V
Source-source On-state Resistance	RSS(on)1	IS = 6.2 A, VGS = 4.5 V	1.6	2.2	2.9	m Ω
	RSS(on)2	IS = 6.2 A, VGS = 3.8 V	1.8	2.5	3.3	
	RSS(on)3	IS = 6.2 A, VGS = 3.1 V	2.1	3.1	5.0	
	RSS(on)4	IS = 6.2 A, VGS = 2.5 V	2.6	4.3	8.5	
Body Diode Forward Voltage	VF(s-s)	IF = 6.2 A, VGS = 0 V		0.7	1.0	V
Input Capacitance ^{*1}	Ciss	VSS = 10 V, VGS = 0 V, f = 1 kHz		2230		pF
Output Capacitance ^{*1}	Coss			410		
Reverse Transfer Capacitance ^{*1}	Crss			330		
Turn-on Delay Time ^{*1,2}	td(on)	VDD = 6 V, VGS = 0 to 4 V		0.8		μs
Rise Time ^{*1,2}	tr	IS = 6.2 A		1.6		
Turn-off Delay Time ^{*1,2}	td(off)	VDD = 6 V, VGS = 4 to 0 V		3.3		μs
Fall Time ^{*1,2}	tf	IS = 6.2 A		2.7		
Total Gate Charge ^{*1}	Qg	VDD = 6 V		17		nC
Gate-source Charge ^{*1}	Qgs	VGS = 0 to 4 V		7		
Gate-drain Charge ^{*1}	Qgd	IS = 12.4 A		4		
Gate Resistance ^{*1}	Rg	f = 1 MHz	400	700	1000	Ω

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Guaranteed by design, not subject to production testing.

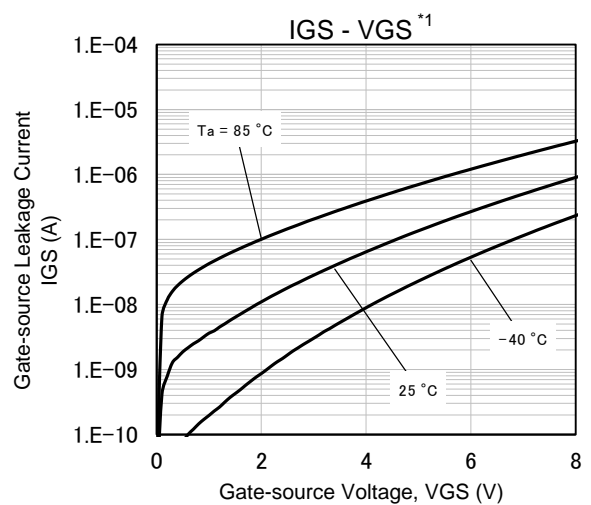
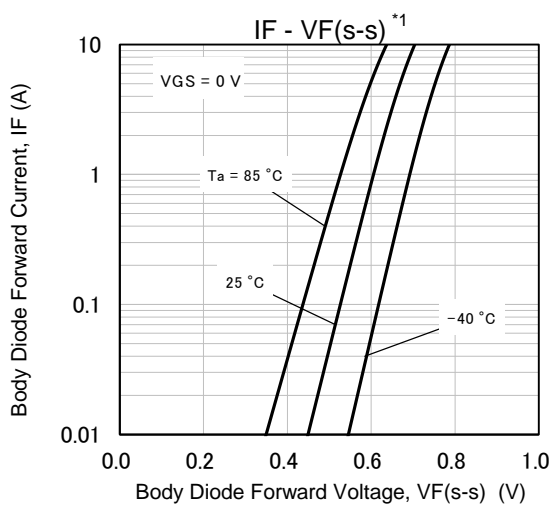
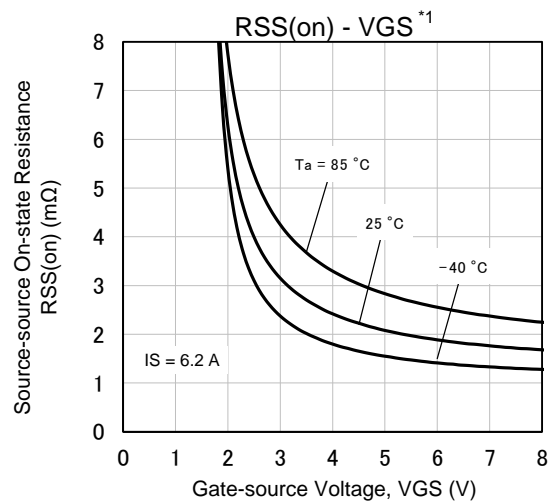
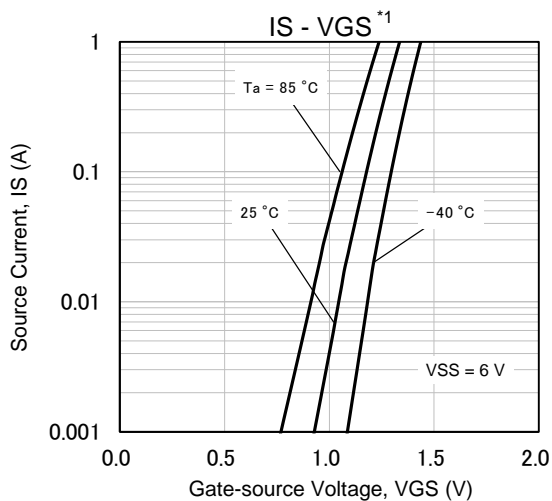
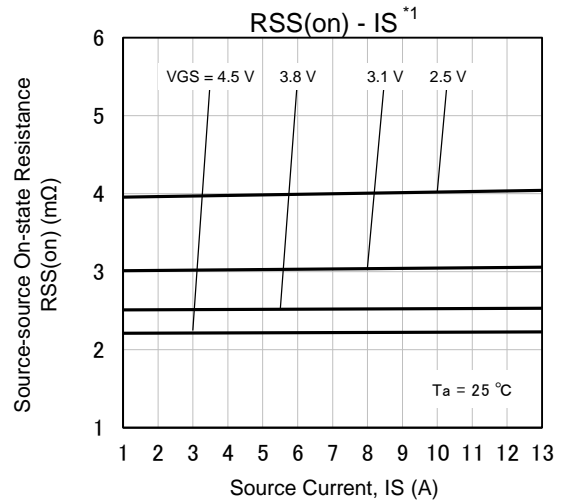
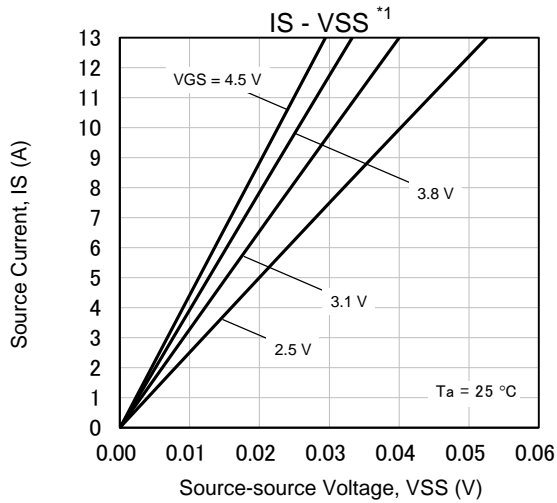
*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time.



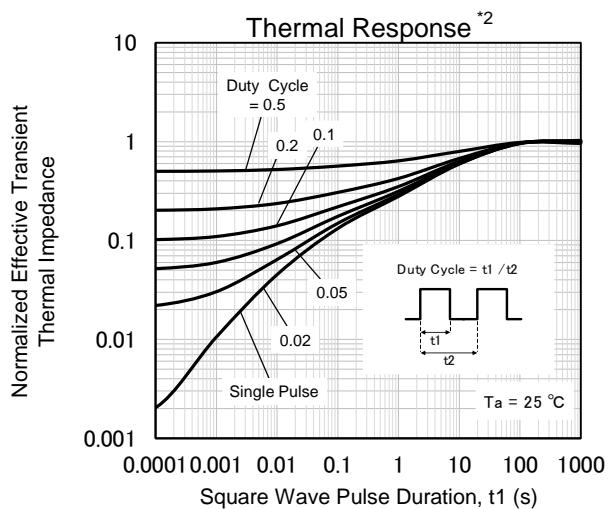
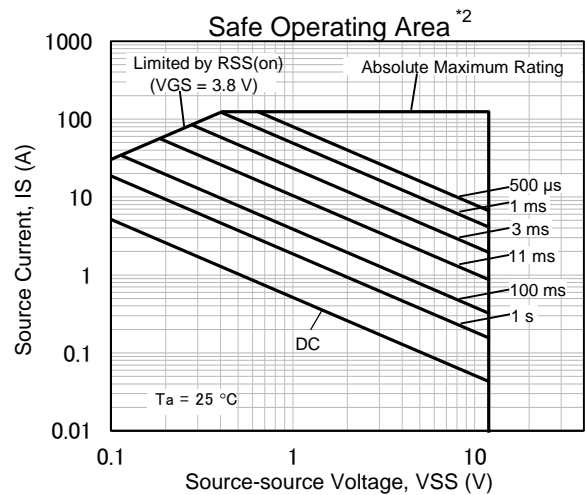
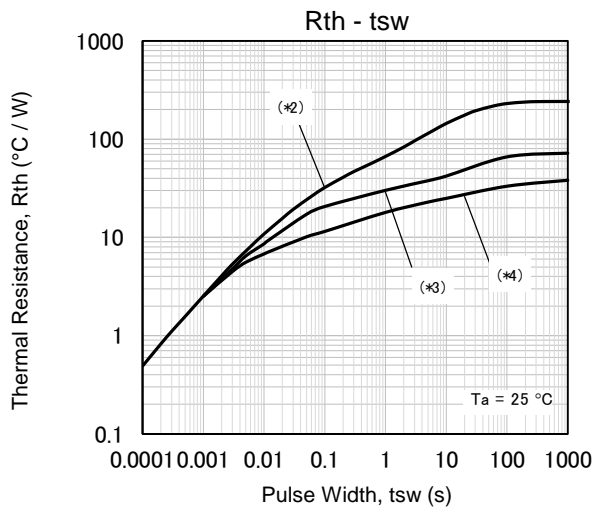
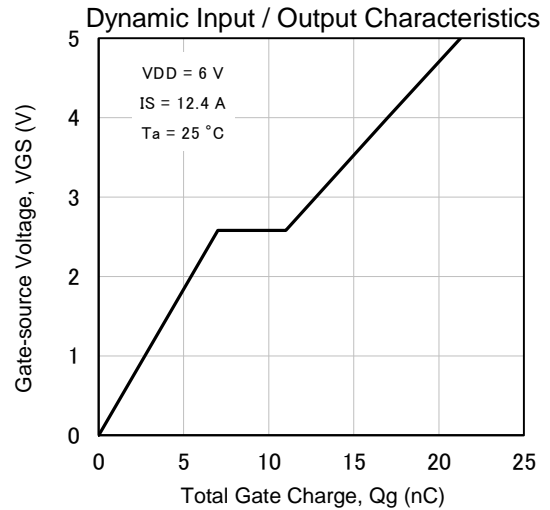
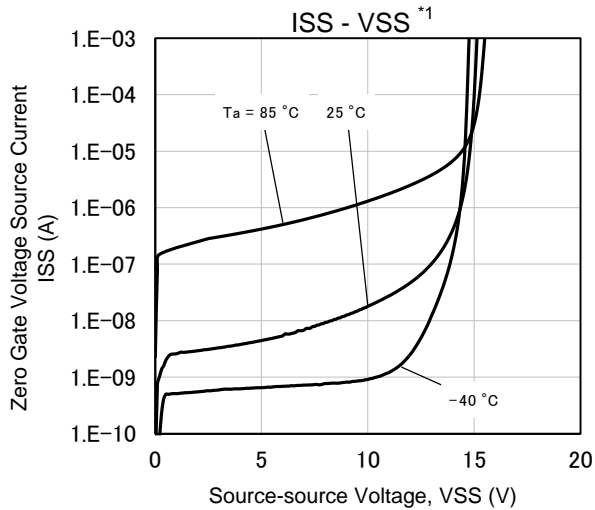
8. ELECTROSTATIC DISCHARGE CHARACTERISTIC $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Standard	Test Type	Symbol	Conditions	Class	Value	Unit
AEC-Q101-001	Human Body Model	HBM	C = 100 pF, R = 1.5 k Ω	H2	> 2 to ≤ 4	kV

9. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)



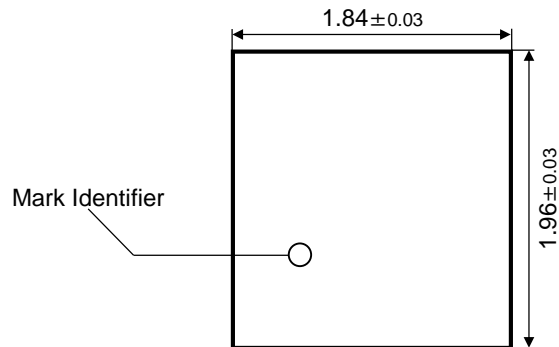
Note

- *1 Pulse measurement.
- *2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm).
FR4 board partially covered with copper pad
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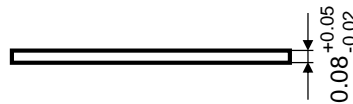
10. OUTLINE

(Top View)

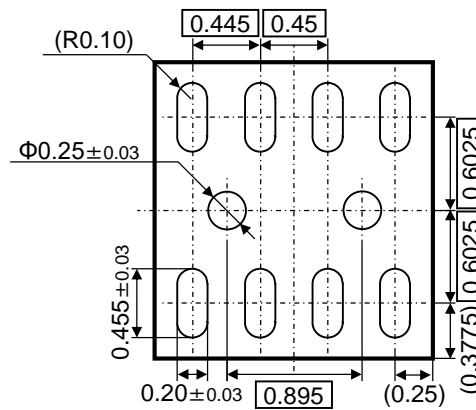
Unit: mm



(Front View)

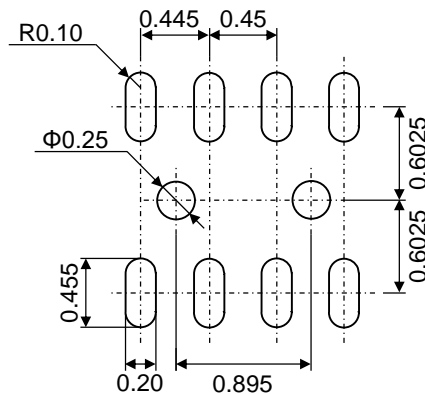


(Bottom View)



11. LAND & STENCIL PATTERN (Reference)

Unit: mm



Important notice:

Solder Mask Defined (SMD) pattern is strongly recommended for pad design.
Please check the information in the Nuvoton WL-CSP Application Notes about mounting process.

12. REVISION HISTORY

Date	Revision	Description
2021.08.31	1.00	1. Initially issued.

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